



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

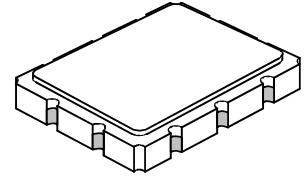


- *Designed for GSM BTS Receiver IF Applications*
- *Compatible with National Semiconductor Chip Set*
- *Very Flexible Impedance Matching*
- *Unbalanced or Balanced Input or Output*
- *9.1 x 7.1 mm Version of the SF1115A-1*
- *Complies with Directive 2002/95/EC (RoHS)*



SF1115A

**199 MHz
SAW Filter**



SM9171-10

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+15	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max. Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_C	1	199.000			MHz
Passband Insertion Loss at fc 1 db Passband Amplitude Ripple over fc±100 kHz Group Delay Variation over fc ±100 kHz	IL	1, 2			7.0	dB
	BW_1		±100			kHz
					0.5	dB _{P-P}
	GDV				500	ns _{P-P}
Rejection Room Temperature fc+800 to fc+400 kHz Room Temperature fc-800 to fc-400 kHz fc-800 to fc-600 and fc+600 to fc+800 kHz fc-30 MHz to fc-800 kHz fc+800 kHz to fc+17 MHz fc-80 MHz to fc-30 MHz fc+17 Mhz to fc+80 MHz		1, 2, 3	10			dB
			10			
			20			
			30			
			30			
			35			
Operating Temperature Range	T_A	1	-35		+85	°C
Frequency Temperature Coefficient	FTC	1		0.032		ppm/°C ²

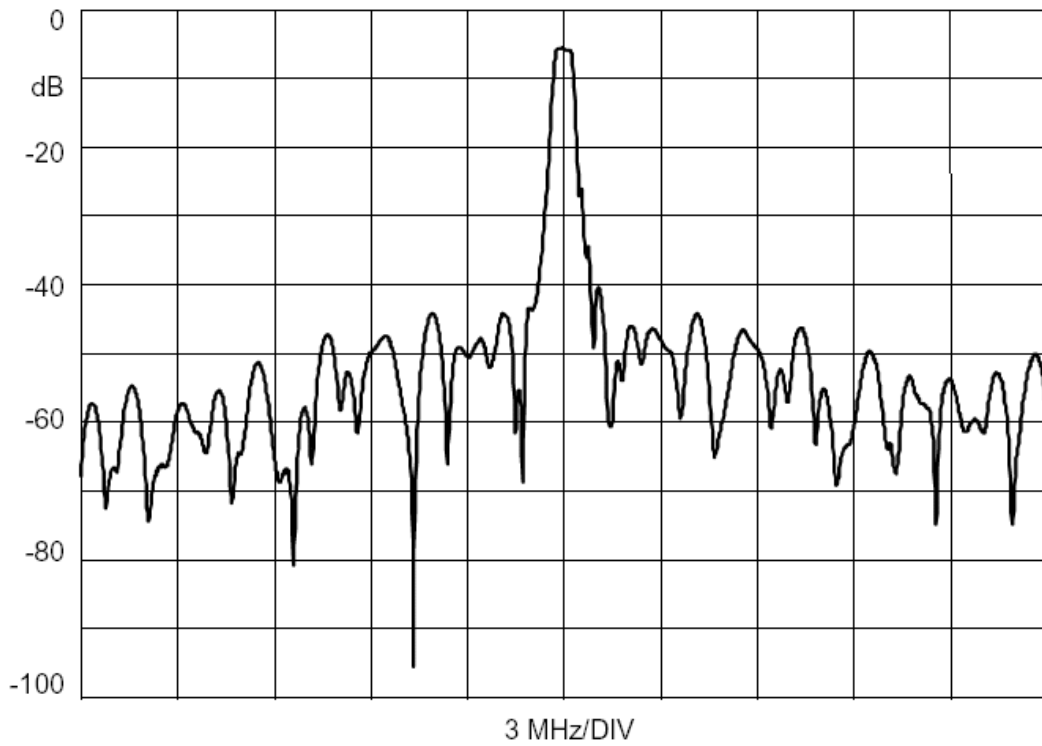
Impedance Matching to 50Ω Unbalanced	External L-C
Impedance Matching to 200Ω Balanced	External L-C
Impedance Matching to 50Ω Input / 400Ω Output	External L-C
Case Style	SMP9171-10 9.1 x 7.1 mm Nominal Footprint
Lid Symbolization (YY = year, WW = week)	RFM SF1115A YYWW



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

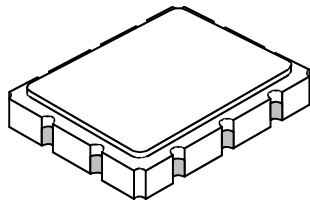
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_C .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. The turnover temperature, T_O , is the temperature of maximum (or turnover) frequency, f_o . The nominal frequency at any case temperature, T_C , may be calculated from: $f=f_o[1-FTC(T_o-T_C)]^2$.
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.



SM9171-10 Case

10-Terminal Ceramic Surface-Mount Case

9.1 x 7.1 mm Nominal Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	8.86	9.09	9.40	0.349	0.358	0.370
B	6.88	7.11	7.40	0.271	0.280	0.291
C		1.91	2.00		0.075	0.079
D		0.99			0.039	
E		0.79			0.031	
H		1.0			0.039	
P		2.54			0.100	

Materials	
Solder Pad Termination	Au plating 30 - 60 pinches (76.2-152 μm) over 80-200 pinches (203-508 μm) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 pinches Thick
Body	Al_2O_3 Ceramic
Pb Free	

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	6
	Return or Input	5
Port 2	Output or Return	1
	Return or Output	10
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot

